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**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

IN RE APPLICATION OF: JOHN M. PEDERSEN *ET AL.*

APPLICATION NO.: 09/823,948

FILED: MARCH 30, 2001

FOR: **DRY CONTACT ASSEMBLIES, METHODS  
FOR MAKING DRY CONTACT  
ASSEMBLIES, AND PLATING MACHINES  
WITH DRY CONTACT ASSEMBLIES FOR  
PLATING MICROELECTRONIC  
WORKPIECES**

EXAMINER: BRIAN L. MUTSCHLER

ART UNIT: 1753

CONF. NO: 7598

#10/C  
w.m.  
6/11/03

**Amendment in Response to Restriction Requirement**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RECEIVED**

**JUN 09 2003**

**TC 1700**

Sir:

In response to the Office Action dated April 30, 2003, please amend the application as reflected in the following listing of claims.

**Amendment to the Claims**

1. (Original) A contact assembly for plating a layer on a microelectronic workpiece, comprising:

C1 a support member having an opening configured to receive a microelectronic workpiece;

a contact system carried by the support member, the contact system having a plurality of electrically conductive contact members projecting inwardly into the opening;

a shield carried by the support member to prevent electroplating solution from engaging the contact members, the shield projecting from the support member to